

Product	Laser diode
Package	RLD84NZJ2

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
	Material acceptance	Preparatory process	Main Process			
LD chip				Acceptance test	Visual	Appearance
Submount				Chips preparation	Braking machine Expander	Appearance Air pressure Temperature
				Acceptance test	Microscope	Appearance
				Die-&wire-bonding(1)	ALDW40	Temperature DB load Ultrasonic power WB load
				Measurement	ALDW40	Probe state I-L characteristics I-V characteristics
Stem				Inspection(1)	Tension gauge	Wire-pull resistivity Peel-off resistivity
Pin Photo Di				Die-&wire-bonding(0)	APDW	Temperature Ultrasonic power
Ag paste				Inspection(0)		PD,DB position Wire-pull resistivity
Bondhing agent				Die-&wire-bonding(2)	ASDW	Peel-off resistivity Temperature DB load Ultrasonic power
				Inspection(2)	Microscope Tension gauge FFP standard Correct monitorscope	Wire-pull resistivity DB load Facet inclination △XYZ

Materials	Flow chart			Name of process	Used equipment & machine	Controlled item
	Material acceptance	Preparatory process	Main Process			
Cap				Can sealing	AACL	Air pressure N2 pressure Humidity
				Inspection for sealing	Cutting nipper Micrometer Correct monitorscope	Weld strength Weld extrusion Degree of decentering
				Products burn-in test	AATB	Set temperature I-L characteristics (100% test)
				Final measurement Marking	ATMS	Temperature I-L characteristics I-V characteristics Positional accuracy FFP Wavelength Appearance (100% test)
				Appearance check	Microscope	Crazing and dirt of lens Flaws of stem In deposition (100% test)
				Quantity treatment	Calculator	Quantity check
				Packing		Slip Indication check
				Shipment inspection		Outer label and contents check
				Packaging		Detailed statement for shipment Packing condition
				Shipment		

Notes

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